

Product Information Dual-Interface Card – Thales DIS

Property	Standard card*
Material	Modified PVC for high temperature usage
Colour	White, opaque
Surface	40 µm PVC Overlay
Dimension	ISO 7810 ID-1
Card Thickness	0,80 ±0,04 mm
Temperature of continuous usage	70 °C
Resistance to temperature (one side fixed)	70 °C
Module contacts	ISO 7816
Surface lamination	glossy, others on request
Connecting technology antenna – module	soldering
Antenna and contact pad technology	Embedded wire and welding
Printed cards	Offset beneath the overlay
Signature panel	transparent (hotstamped), others on request
Magnetic stripe	300 Oe, 2750 Oe, 4000 Oe
Subsequent printability	Thermotransfer or dye sublimation processes
Supplied material	6- or 8-contact modules from NXP and Infineon others on request

* Possible options are always subject to feasibility, especially in combination with other options

NXP Smart MX2 P60 / Smart MX3 P71 (ISO 14443A)
OS: JCOP / MTCOS / TCOS

Infineon SLE78xx // SLJ32xx // SLJ 52 (ISO 14443 A/B)
OS: JTOP / CardOS / TCOS

and applets on these processors for example Legic Card-in-Card / Calypso / Cipurse

Additional features:
please turn the page



Magnetic Stripes



Signature Panels



Holograms



Thermo-Re-Writable Foils



Special Prints & Effects



Number Printing / Lasering



SIM Punches / Special Cards



Lamination Surfaces

